



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Mini Top View LEDs EAPL2214GA0

PRELIMINARY



Features

- White SMT package.
- Optical indicator.
- Wide viewing angle.
- Soldering methods: reflow soldering
- Available on tape and reel
- Pb-free
- The product itself will remain within RoHS compliant version.

Applications

- Optical indicators.
- Coupling into light guides.
- Backlighting (LCD, cellular phones, switches, keys, displays, illuminated advertising, and general lighting).
- Coupling into light guides; Interior automotive lighting (e.g. dashboard backlighting, etc.).

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Brilliant Yellow Green	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	12	V
Forward Current	I_F	30	mA
Power Dissipation	P_d	84	mW
Junction Temperature	T_j	125	°C
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +80	°C
Thermal Resistance	$R_{th\ J-A}$	500	K/W
	$R_{th\ J-S}$	300	K/W
ESD (Classification acc. AEC Q101)	ESD_{HBM}	500	V
	ESD_{MM}	200	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	35.5	-----	90	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}	-----	120	-----	deg	I _F =20mA
Peak Wavelength	λ _p	-----	575	-----	nm	I _F =20mA
Dominant Wavelength	λ _d	-----	----	-----	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ	-----	15	-----	nm	I _F =20mA
Forward Voltage	V _F	1.75	----	2.8	V	I _F =20mA
Reverse Current	I _R	-----	-----	10	μA	V _R =12V
Temperature coefficient of λ _p	TC _{λ_p}	---	0.06	---	nm/K	I _F =20mA
Temperature coefficient of λ _d	TC _{λ_d}	---	0.4	---	nm/K	I _F =20mA
Temperature coefficient of VF	TC _V	---	-2.3	---	mV/K	I _F =20mA

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.1V

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
N2	35.5	45	mcd	I _F =20mA
P1	45	57		
P2	57	72		
Q1	72	90		

Note: Tolerance of Luminous Intensity: ±11%

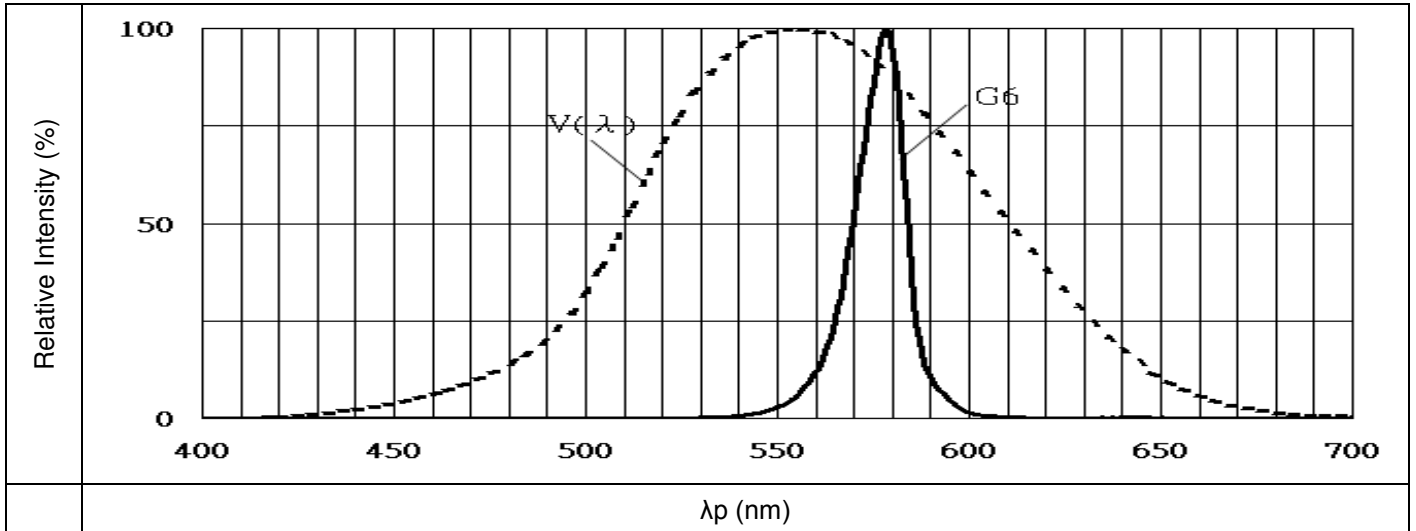
Bin Range of Dominant Wavelength

Group	Bin Code	Min.	Max.	Unit	Condition
A	C16	569.5	571.5	nm	I _F =20mA
	C17	571.5	573.5		
	C18	573.5	575.5		
	C19	575.5	577.5		

Note: Tolerance of Dominant Wavelength: ±1nm

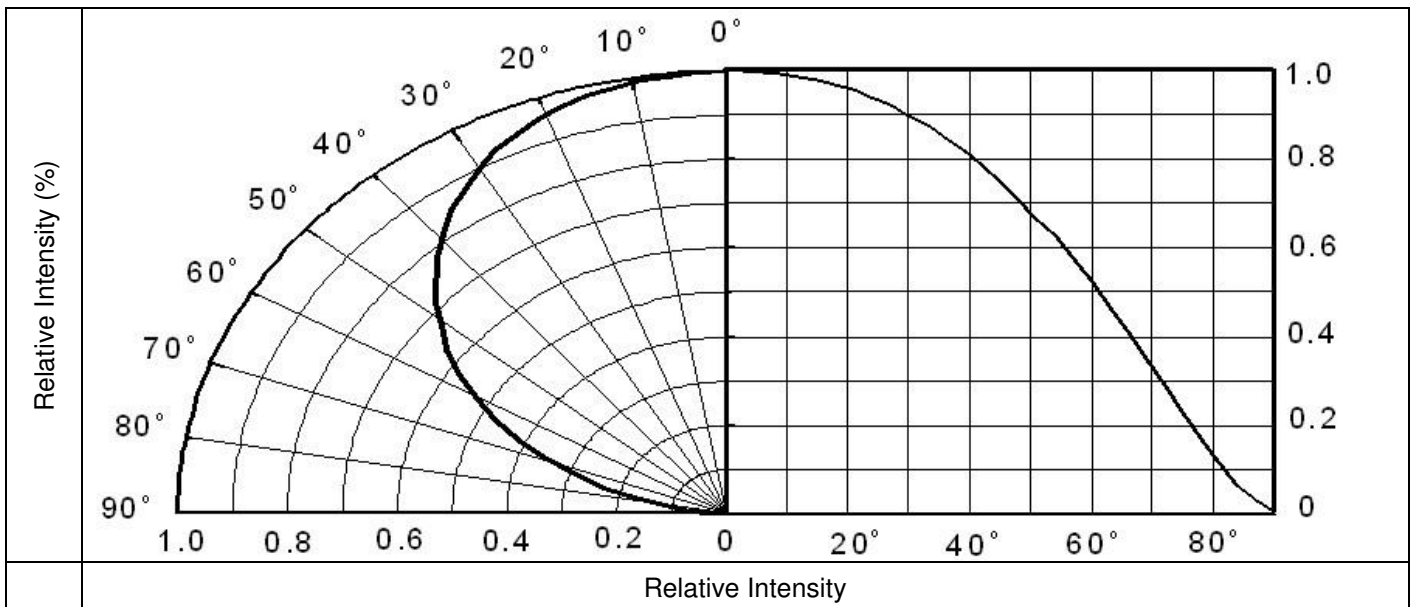
Typical Electro-Optical Characteristics Curves

Typical Curve of Spectral Distribution

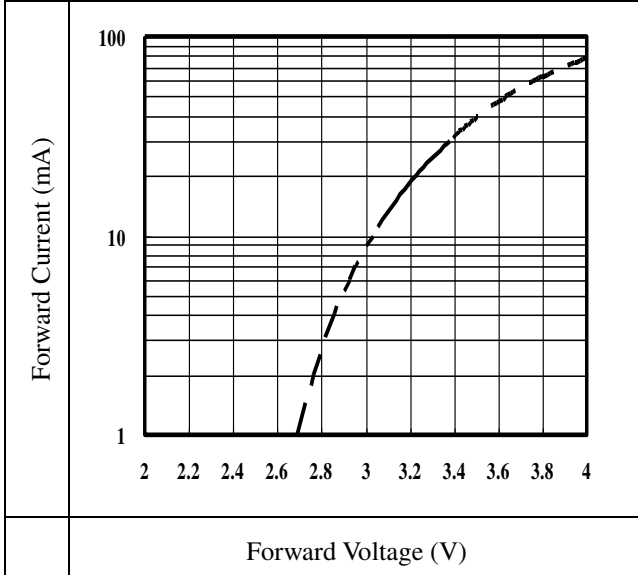


Note: $V(\lambda)$ =Standard eye response curve;

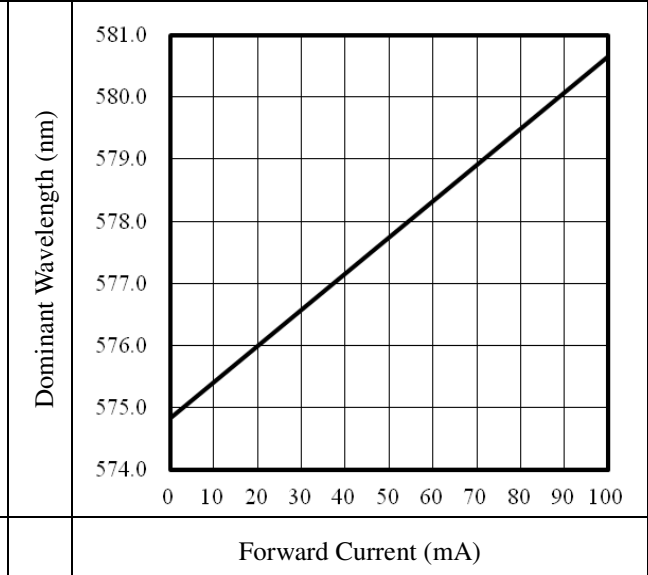
Diagram Characteristics of Radiation



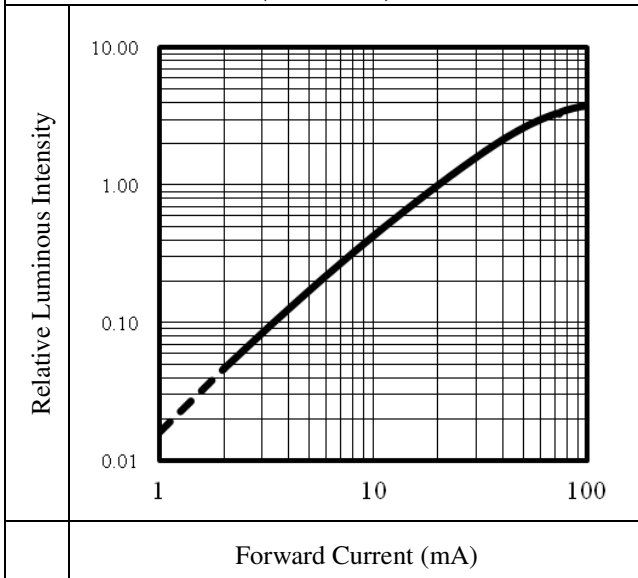
Forward Current vs. Forward Voltage
 (Ta=25°C)



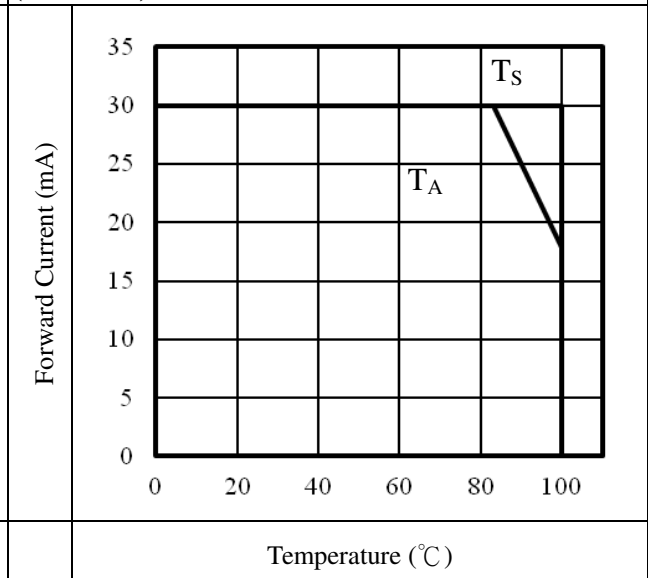
Dominant Wavelength vs. Forward Current
 (Ta=25°C)



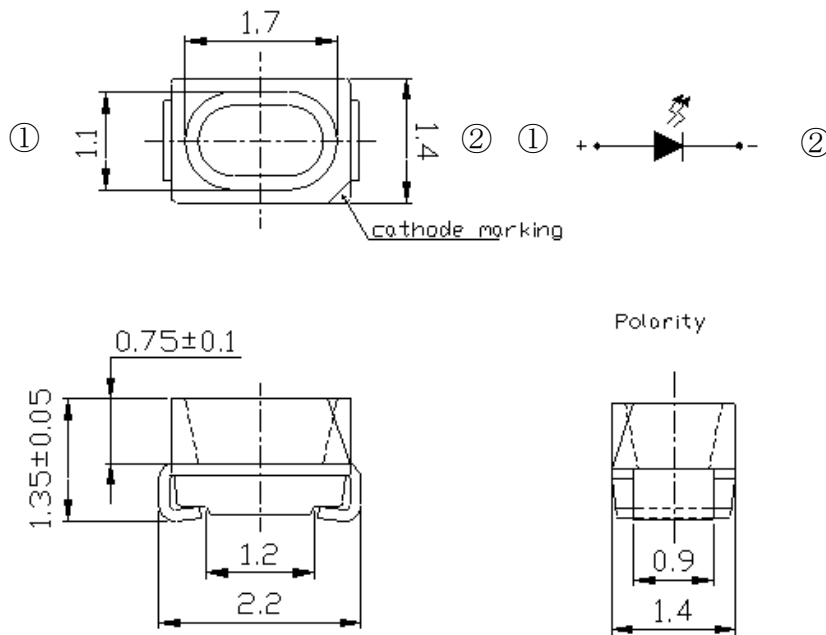
Relative Luminous Intensity vs. Forward Current
 (Ta=25°C)



Max. Permissible Forwarded Current
 (Ta=25°C)



Package Dimension



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

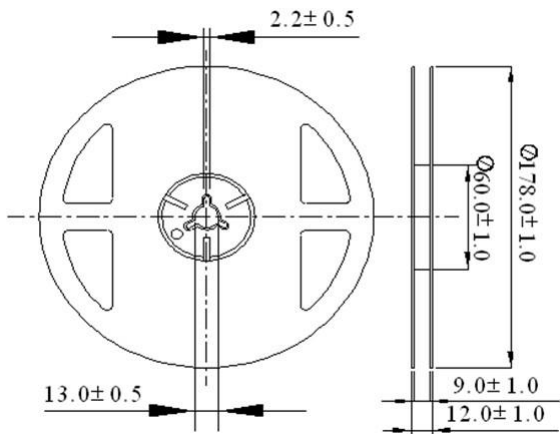
Moisture Resistant Packing Materials

Label Explanation

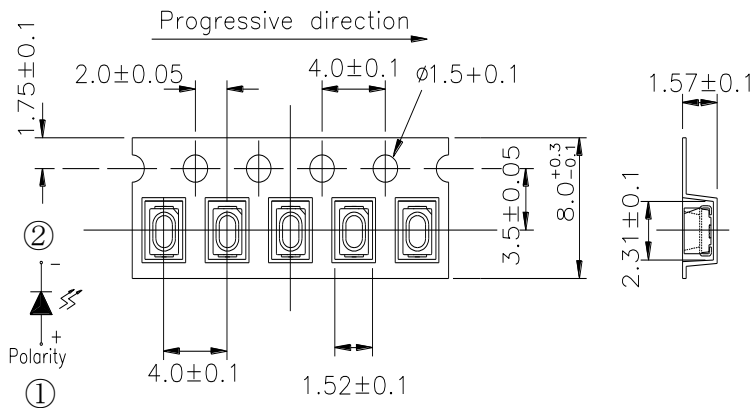


- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions

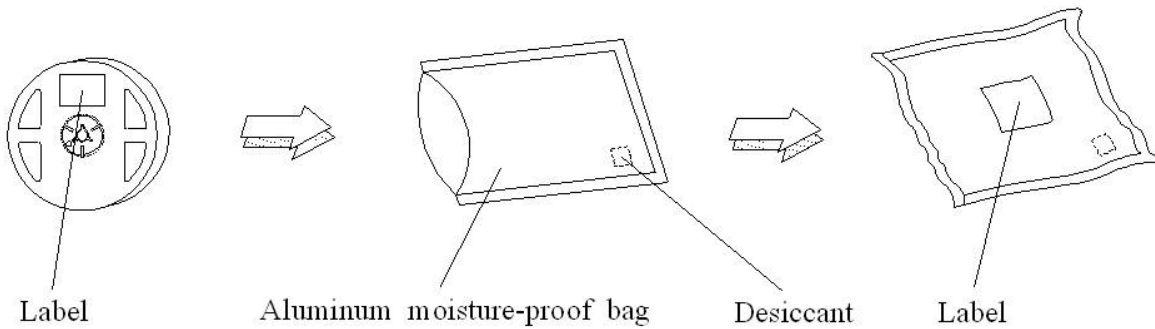


Carrier Tape Dimensions: Loaded Quantity 3000 pcs Per Reel



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

Moisture Resistant Packing Process

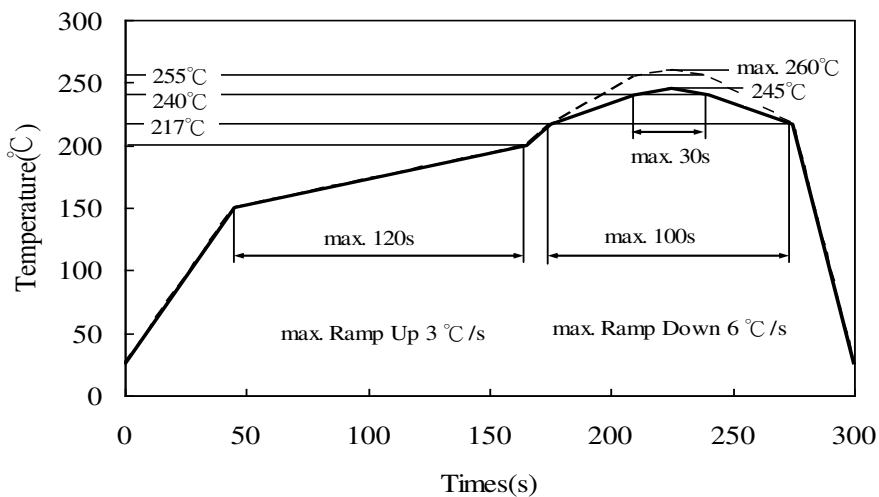


Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

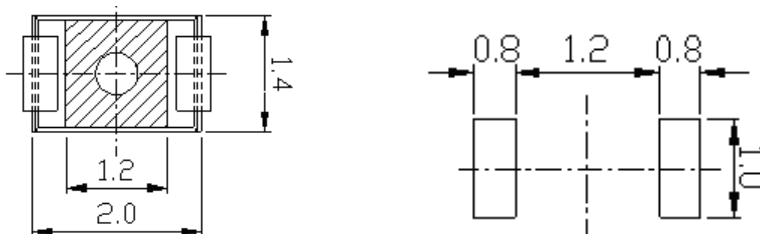
Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



1.2 (B) Recommend soldering pad



Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

3. Storage

3.1 Moisture proof bag should only be opened immediately prior to usage.

3.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.

3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.

3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350°C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

5. Usage

Do not exceed the values given in this specification.